TE Internal #: 2-2822979-4

LGA Sockets, LGA 3647, 3647 Position, .039 in / .034 in [.99 mm / .

86 mm] Centerline, Surface Mount Solder Ball Mount

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Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 Sockets



IC Socket Type: LGA 3647

Connector System: Board-to-Board

Number of Positions: 3647

Contact Mating Area Plating Material Thickness: [30 µin]

Centerline (Pitch): .86 mm, .99 mm [.034 in, .039 in]

All LGA 3647 Sockets (8)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	3647
Grid Spacing	.9906 x .8585 mm[.039 x .0338 in]
Body Features	
Frame Style	Square
Contact Features	
Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 µin
Contact Current Rating (Max)	.5 A
Mechanical Attachment	

PCB Mounting Style

Connector Mounting Type

Surface Mount Solder Ball

Board Mount



Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.86 mm, .99 mm[.034 in][.039 in]
Usage Conditions	
Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tray
Other	
Socket Connector Comment	Lead-Free Solderball

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts













Customers Also Bought







Documents

Product Drawings

LGA3647-1 SOCKET-P1 KIT FOR ODM (30U AU)

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-2822979-4_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-2822979-4_C.3d_igs.zip



English

Customer View Model

ENG_CVM_CVM_2-2822979-4_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

LGA 3647 Socket Product Flyer

English

Product Specifications

Application Specification

English